**SOT-143**

**CASE 318A-06**

**ISSUE U**

**DATE 07 SEP 2011**

**NOTES:**

2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, AND GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
6. DATUMS A AND B ARE DETERMINED AT DATUM H.

**GADGET MARKING DIAGRAM**

XXX = Specific Device Code
M = Date Code
* = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, “G” or microdot “*”, may or may not be present.

**DIMENSIONS:** MILLIMETERS

<table>
<thead>
<tr>
<th>DIM</th>
<th>MIN</th>
<th>MAX</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.05</td>
<td>0.12</td>
</tr>
<tr>
<td>b</td>
<td>0.30</td>
<td>0.51</td>
</tr>
<tr>
<td>B</td>
<td>0.75</td>
<td>0.94</td>
</tr>
<tr>
<td>C</td>
<td>0.08</td>
<td>0.20</td>
</tr>
<tr>
<td>D</td>
<td>2.80</td>
<td>3.05</td>
</tr>
<tr>
<td>E</td>
<td>2.10</td>
<td>2.34</td>
</tr>
<tr>
<td>E1</td>
<td>1.20</td>
<td>1.40</td>
</tr>
<tr>
<td>e</td>
<td>1.90</td>
<td>BSC</td>
</tr>
<tr>
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<td>BSC</td>
</tr>
<tr>
<td>L</td>
<td>0.35</td>
<td>0.70</td>
</tr>
<tr>
<td>L2</td>
<td>0.25</td>
<td>BSC</td>
</tr>
</tbody>
</table>

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**RECOMMENDED SOLDERING FOOTPRINT**

 Dimensions: MILLIMETERS

<table>
<thead>
<tr>
<th>DIM</th>
<th>MIN</th>
<th>MAX</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.20</td>
<td>0.20</td>
</tr>
<tr>
<td>C</td>
<td>0.96</td>
<td>0.96</td>
</tr>
<tr>
<td>D</td>
<td>0.54</td>
<td>0.54</td>
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</tbody>
</table>

**STYLES:**

- **STYLE 1:**
  1. COLLECTOR
  2. Emitter
  3. Emitter
  4. BASE

- **STYLE 2:**
  1. SOURCE
  2. DRAIN
  3. GATE 1
  4. GATE 2

- **STYLE 3:**
  1. GROUND
  2. SOURCE
  3. INPUT
  4. OUTPUT

- **STYLE 4:**
  1. OUTPUT
  2. SOURCE
  3. INPUT
  4. OUTPUT

- **STYLE 5:**
  1. SOURCE
  2. DRAIN
  3. GATE 1
  4. GATE 2

- **STYLE 6:**
  1. SOURCE
  2. RF IN
  3. RF OUT

- **STYLE 7:**
  1. SOURCE
  2. GATE
  3. DRAIN
  4. SOURCE

- **STYLE 8:**
  1. SOURCE
  2. GATE
  3. SOURCE
  4. N/C

- **STYLE 9:**
  1. GND
  2. RF IN
  3. VREG
  4. RF OUT

- **STYLE 10:**
  1. DRAIN
  2. N/C
  3. SOURCE
  4. GATE

- **STYLE 11:**
  1. SOURCE
  2. GATE 1
  3. GATE 2
  4. DRAIN

(Note: Microdot may be in either location)